Product End-of-Life Disassembly Instructions

Marketing Name / Model
[List multiple models if applicable.]
HP Z27 – 27-inch 4K UHD Display

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEE).

NOTE: Recyclers should sort plastic materials into resin streams for recycling based on the ISO 11469 plastic marking code on the plastic part. For any questions on plastic marking, please contact HP’s Sustainability Contact.

1.0 Items Requiring Selective Treatment
1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm Function key BD, IF BD, POWER BD, LED Driver BD</td>
<td>4</td>
</tr>
<tr>
<td>Batteries, excluding Li-Ion batteries.</td>
<td>All types including standard alkaline, coin or button style batteries</td>
<td>0</td>
</tr>
<tr>
<td>Li-Ion batteries. Include all Li-Ion batteries if more than one is provided with the product (such as a detachable notebook keyboard battery, RTC coin cell, etc.)</td>
<td>Battery(ies) are attached to the product by (check all that apply with an “x” inside the “[]”): [ ] screws [ ] snaps [ ] adhesive [ ] other. Explain NOTE: Add detailed removal procedures including required tools in the sections 3.1/3.2.</td>
<td>0</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td>0</td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps Panel</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td>Power BD only (C805)</td>
<td>1</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td>USB cable, Display cable, Power cord</td>
<td>3</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants (not including PCBs or PCAs already listed as a separate item)</td>
<td></td>
<td>0</td>
</tr>
</tbody>
</table>

HPI instructions for this template are available at EL-MF877-01
<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service</td>
<td>0</td>
</tr>
<tr>
<td>(gel/paste) and toner</td>
<td>stations.</td>
<td></td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components, parts and materials containing refractory ceramic fibers</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components, parts and materials containing radioactive substances</td>
<td></td>
<td>0</td>
</tr>
</tbody>
</table>

### 2.0 Tools Required
List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Description #1 SCREW DRIVER(PHILLIPS HEAD)</td>
<td>#0</td>
</tr>
<tr>
<td>Description #2 SCREW DRIVER(PHILLIPS HEAD)</td>
<td>#1</td>
</tr>
<tr>
<td>Description #3 SCREW DRIVER(PHILLIPS HEAD)</td>
<td>#2</td>
</tr>
</tbody>
</table>

### 3.0 Product Disassembly Process
3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment including the required steps to remove the external enclosure:

1. Remove Stand Base From Display Head
2. Remove Rear Cover From Display Head
3. Remove Bracket Assy From Display Head
4. Remove Mid cover From Display Head
5. Remove Front Cover From Display Head
6. Disassemble Front Chin
7. Disassemble Bracket ASSY
8. Disassemble Stand ASSY
9. Disassemble Panel ASSY

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
External Electric Cables Dissecting Process

1. Remove Cable From Display Head.
Remove Stand Base From Display Head

2. Pull the release button

3. Remove Stand Base From Display Head.
4. Remove Rear Cover From Display Head.
Remove Back cover from Display Head

5. Remove Back cover from display head

Remove 3 screws
Remove 5 screws
Remove 4 screws
6. Remove Bracket Assy from head
Remove Mid-cover / bracket from head

7. Remove Mid-cover from head
Disassemble Bracket ASSY

- Remove Screws
- Remove Screws
- Remove cable
- Gasket and thermal pad
Disassemble Bracket ASSY

Remove heat sink screws

Remove screws

Remove screws
Disassemble Rear cover

Remove Function key
Disassemble Front Chin

Remove Function key
Disassemble Stand ASSY

Remove 4 screws

Remove screw

Remove screw
And rubber

Separate base-top cover

Separate base-bottom cover

Remove 4 screws

Remove screw
Disassemble Stand ASSY

Remove screw

Separate VESA cover
Disassemble Stand_Pivot ASSY

Remove screw
Disassemble Stand ASSY

1. Remove screw
2. Separate
3. Lift rear cover
4. Remove screw
5. Remove screw
6. Remove screw
7. Remove screw
8. Remove screw and lift front cover
Method of LCM disassembly on LM270WR3

Step 1: Loosen the Screw (3 Points)
Step 2: Remove the C/Shield
Step 3: Detach the Black Tape (6 points)
Step 4: Separate Board Ass'y + G/Panel
Step 5: Remove Optical material (Sheet + LGP + Reflector)
Step 6: Separate LGP holder from C/Bottom (4 Points)
Step 7: Separate C/Board from C/Bottom
Step 8: Separate LED Array from C/Bottom
Final: LED Array & C/Board & C/Bottom & LGP Holder